

IN THE ABSTRACT

Please replace the abstract with the following paragraph:

The present invention provides a packaged semiconductor device that includes two semiconductor die. The first semiconductor die is attached to a package substrate using adhesive. A first set of wire bonds electrically connect the first semiconductor die to the package substrate. A first layer of encapsulant extends over the first semiconductor die and over the first set of wire bonds. A second semiconductor die is attached to the first layer of encapsulant using adhesive. A second set of wire bonds electrically connect the second semiconductor die to the package substrate. A second layer of encapsulant extends over the second semiconductor die and over the second set of wire bonds.


CONCLUSION

Applicant respectfully asserts that no new matter has been added by the present amendment. Applicant earnestly solicits allowance of Claims 1-20.

The Examiner is urged to contact Applicant's undersigned representative if the Examiner believes such action would expedite resolution of the present Application.

Respectfully Submitted,

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Date



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